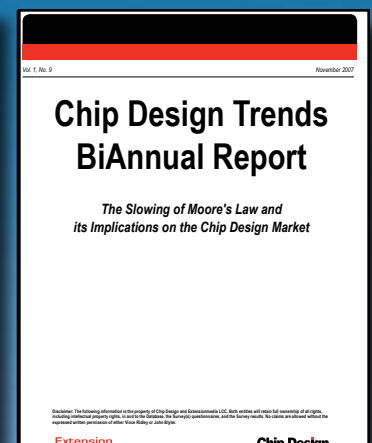


# Target Your Marketing

to Power Users in the \$4.0 Billion  
Advanced IC Design Market



The ONLY Media Network Dedicated  
to the IC Design Market

Magazine • Email Newsletters • Blogs and Podcasts • Online Marketing  
Resource Catalogs • Lead Generation • Conference • Research • Custom Publishing

[www.chipdesignmag.com](http://www.chipdesignmag.com)

2008 Media Kit

Affiliate Sponsors:



Published by  
**Extension**  
MEDIA

# Editorial Focused Entirely on the Advanced Design Market

## Editorial Leadership

**John Blyler**, Editorial Director



John is a leading authority on the technological issues that drive today's chip, advanced EDA and semiconductor industries.

He has worked in the electronics industry for over 24 years.

Aside from editorial experience with the IEEE and technical trade journals, he has also co-authored books on systems-level design (IEEE-Wiley) and RF Design (Elsevier). John remains an affiliate professor in Systems Engineering at Portland State University.

**Jim Kobylecky**, Managing Editor

Jim has worked as a technical writer and copy editor for such high-tech firms as Mentor Graphics, Tektronix, Credence, Merix and Intel.

**Pallab Chatterjee**, Regional Managing Editor

Pallab is a long-time consultant in the EDA, Mixed Signal and custom design space.

**Dave Bursky**, Senior Editor,

Dave is a recognized expert in the EDA/chip design technology. He is also the Technical Editorial Manager at Maxim Integrated Products.

**Clive "Max" Maxfield**, Executive Editor, *Chip Design / iDesign*

Clive is a well-known writer and speaker in the EDA community. He is the President of TechBites Interactive ([www.techbites.com](http://www.techbites.com)).

**Erach Desai**, Chief Analyst

Erach is a prominent EDA/semiconductor analyst with many years of Wall Street experience as an equity analyst for Credit Suisse First Boston, Alex Brown & Sons, and SoundView Technology Group.

**Geoffrey James**, Business Editor

Geoffrey has written for national publications including *Wired*, *Business 2.0*, *Electronic Business*, *The New York Times* and others.

**Cheryl Ajluni**, Contributing Editor

Cheryl is a contributing editor and freelance technical writer. She has over 12 years experience covering the high-tech industry.

**Jack Browne**, Contributing Editor

Jack has over 30 years of experience. He serves as Technical Director (contractor) of *Microwaves & RF* magazine.

**Nicole Freeman**, Technology Editor

Nicole's editorial experiences include technology-focused publications for *AlwaysOn*, *IBDNetworks*, *GameSpot* (CNET Networks), and *ZDNet*.

## Editorial Board

**Tom Anderson**, *Marketing Director, Cadence*

**Cheryl Ajluni**, *Consultant, Custom Media Solns*

**Karen Bartleson**, *Stds Manager, Synopsys*

**Chuck Byers**, *Director Communications, TSMC*

**Rich Faris**, *Vice President Marketing, Real Intent*

**Kathryn Kranen**, *CEO, Jasper Design Automation*

**Barry Marsh**, *Vice President Marketing, Actel*

**Tom Moxon**, *Consultant, Moxon Design*

**Walter Ng**, *Senior Director, Chartered Semi*

**Scott Sandler**, *CEO, Novas Software*

**Steve Schulz**, *President, Si2*

**Adam Traidman**, *President, ChipEstimate*

**Chip Design** covers all of the technical challenges and implementation options that engineers face in the development and manufacture of today's complex integrated circuits (IC). Key focus areas includes the design of complex System-on-chips (SoCs), Electronic Design Automation (EDA) tools that enable SoC design and the semiconductor manufacturing process as it affects the design of SoCs including FPGAs and other programmable devices.

## 2008 Chip Design Editorial Calendar

Issue	Focus Report	Key Editorial Topics	Show Distribution	Ad Close	Materials Deadline
Dec/Jan (2007/2008) (Print/Online)	• Buyers' Guide	• FPGA Prototyping • Power Systems • IP Issues • Wireless-RF	• Embedded World • DesignCon • DVCon	Dec. 14	Dec. 17
Feb (Print/Online)	• Focus Report: Chip-Package_Board Co-Design -Verification  • Special Insert	• Video Programming • Multicore Design Tools • Semi Interconnect Intergration • IP Integration  • Cadence/ Partners Interoperability Guide	• Multicore Expo • DATE • ISQED	Feb. 4	Feb. 7
Mar (Online)	• Focus Report:Defense Apps  • Special Insert	• Security Issues • MEMS EDA Tools • Semiconductor Adv Packaging • Chip-Package-Board  • Programmable Logic Devices (PLDs)		Feb. 29	March 3
April (Print/Online)	• Chip Design vs. EDA Tools  • Special Insert	• Embedded SoCs • Nanotechnology Tools • Semiconductor DFM/DFY • Wireless Development  • IP Design & Verification	• ESC Silicon Valley	Mar. 28	April 2
May (Online)	• Collaboration Models-Design and Foundries  • Special Insert	• High Performance FPGA • System Level Design • Semiconductor Thermal Management • Power  • Analog-RF-Wireless Design		April 21	April 25
June (Print/Online)	• Design-Manufacture Variability  • Special Insert	• Programmable Hardware • System Languages • Semiconductor Metrology • IP Metrics  • Annual Product/Services Catalog	• DAC • MTTs • SEMICON	May 19	May 22
July (Online)	• Chip Design Forecast  • Special Insert	• IP for FPGAs • Low-Power Design • Semi Through-Silicon Vias • Analog-Wireless  • DFM/DFY			
Aug (Print/Online)	• Analog Integration  • Special Insert	• PCB Design • Network on Chip • Semiconductor Lithography • Memory  • Mentor Partners Interoperability Guide	• ESC Boston • ARM Conference • PCB West	August 1	August 4
Sept (Online)	• Hardware vs Software  • Special Insert	• Verification for Programmable Devices • System Level Design • New Semiconductor Materials • Hardware vs Software Reuse  • Verification and Debug		Sept. 5	Sept. 10
Oct (Print/Online)	• Chip Design 5 Year Anniversary - A look back and forward  • Special Insert	• High Performance FPGAs • EDA Verification Trends • Semi Advanced Processes • Collaborative Platforms • Synopsys/ Partners Interoperability Guide	• ITC • ICCAD • Chip-Package-Board	Oct. 1	Oct. 3
Nov (Online)	• Career Trends  • Special Insert	• ASIC Prototyping • ESL Tools • Semi Low-K-Dielectrics • Analog-RF-Wireless  • Top 20 Technologies and Gadgets		Nov. 3	Nov. 6
Dec (Print/Online)	• Buyer's Guide  • Special Insert	• Consumer Applications • DSP Designs • Semi Yield Management • Analog-RF-Wireless • Buyer's Guide		Dec. 1	Dec. 5

# Email Newsletters – Reach Targeted Audiences with Relevant Content and News

## Email Newsletter Calendar 2008



### Chip Designer e-Newsletter 30,000+ Subscribers

System-on-Chip (SoC) digital and analog designers, system architects, IP integrators, DFM and verification engineers will benefit from the latest news, industry viewpoints and technical articles. Covers such timely topics as ESL, IP, analog mixed signal, power, DFM-DFY, nanotechnology and more.

### FPGA Developer e-Newsletter 45,000+ Subscribers

Keeps design and test engineers updated on the latest products and technology advances in the growing world of FPGAs, PLDs and Structured ASICs. All aspects of hardware implementation, EDA software and IP design-test issues are covered.



### IP Designer – Integrator e-Newsletter 25,000+ Subscribers

Intellectual Property (IP) design and integration remains one of the hottest trends in the chip industry. Coverage includes trends in analog-digital, core-memory, design, verification, integration and qualification of IP in the SoC space.

### Chip-Package-Board e-Newsletter 25,000+ Subscribers

True system-level coverage of critical chip-package-board topic like system codesign-coverification, IP reuse, System-in-Package (SiP) issues, packaging challenges (like thermal, substrate, and pin efficiency), hardware-software and analog-digital trade-offs that span the whole system.



### Newsletter marketing options:

- **Roadblock/Exclusive**—limited to one sponsor-468x60 banner at top center position; side banner 125x up to 728; up to three text ads; up to five industry announcements. Optional bonus: additional distribution to your email lists (up to 20,000).
- **Platinum**—Leaderboard 728x90 banner at top center position and first 100 word text ad position and two trackable headline links within the newsletter.
- **Gold**—Top right skyscraper (120x600) banner position, second 75 word text ad position and one trackable headline links within the newsletter.
- **Silver**—Top 125x125 side banner position, second 75 word text ad position and one trackable headline links within the newsletter.

Chip Designer newsletter			
Issue	Feature Topic	Ad Close	Materials
Jan'08	Power	Jan 10	Jan 8
Feb'08	SoC Design	Feb 7	Feb 5
Mar'08	Multicore Design	Mar 6	Mar 4
Apr'08	IP Integration	Apr 10	Apr 8
May'08	Programmable HW	May 8	May 6
Jun'08	Analog-RF-Wireless	Jun 5	Jun 3
Jul'08	Green Design	Jul 10	Jul 8
Aug'08	IP Challenges	Aug 7	Aug 5
Sep'08	Lithography	Sep 11	Sep 9
Oct'08	Advanced Chip Verification	Oct 9	Oct 7
Nov'08	Design-for-Manufacturability	Nov 6	Nov 4
Dec'08	Design-for-Yield	Dec 4	Dec 2

FPGA Developer newsletter			
Issue	Feature Topic	Ad Close	Materials
Jan'08	Design/Verif in Consumer Electronics	Jan 3	Dec 30
Feb'08	Optimizing FPGA Design	Jan 31	Jan 29
Mar'08	FPGA/PCB Integration	Feb 28	Feb 26
Apr'08	Using FPGAs with embedded	Apr 3	Apr 1
May'08	IP/Reuse Trends	May 1	Apr 29
Jun'08	RF-Wireless Apps	May 29	May 27
Jul'08	Development Tools	Jul 3	Jul 1
Aug'08	Prototyping with FPGAs	Jul 31	Jul 29
Sep'08	High-Speed I/O Issues	Sept 4	Sept 2
Oct'08	Automotive Design/Verif	Oct 2	Sept 30
Nov'08	Advanced Verification	Oct 30	Oct 28
Dec'08	High-Speed Computing	Nov 25	Nov 26

IP Designer-Integrator newsletter			
Issue	Feature Topic	Ad Close	Materials
Jan'08	IP Trends	Jan 24	Jan 22
Feb'08	IP Interconnect	Feb 21	Feb 19
Mar'08	Interface IP	Mar 20	Mar 18
Apr'08	IP Standards	Apr 24	Apr 22
May'08	Analog Wireless	May 22	May 20
Jun'08	IP Metrics	Jun 19	Jun 17
Jul'08	Memory IP	Jul 24	Jul 22
Aug'08	Interface IP - Wireless	Aug 21	Aug 19
Sep'08	Core IP	Sept 25	Sept 23
Oct'08	Verification IP	Oct 23	Oct 21
Nov'08	Interface IP	Nov 20	Nov 18
Dec'08	Low Power IP	Dec 18	Dec 16

Chip-Package-Board Designer newsletter			
Issue	Feature Topic	Ad Close	Materials
Jan'08	FPGA-Board	Jan 17	Jan 15
Feb'08	Multicore Issues	Feb 14	Feb 12
Mar'08	Stacked Die	Mar 13	Mar 11
Apr'08	Interconnect	Apr 17	Apr 15
May'08	Analog-Wireless	May 15	May 13
Jun'08	IP Integration	Jun 12	Jun 10
Jul'08	Trends	Jul 17	Jul 15
Aug'08	Package Issues	Aug 14	Aug 12
Sep'08	Bonding Issues	Sep 18	Sep 16
Oct'08	Verification IP	Oct 16	Oct 14
Nov'08	Interface IP	Nov 13	Nov 11
Dec'08	System Trends	Dec 11	Dec 9

# Targeted Online Advertising and Lead Generation

## Chip Design Website

Stay on top of the latest technical product news, read about today's technology trends, find detailed technical articles, enjoy techie-style blogs and more at [www.chipdesignmag.com](http://www.chipdesignmag.com).

## Targeted Banner Options

Maximum exposure across [www.chipdesignmag.com](http://www.chipdesignmag.com) with banners including:

- Leaderboards (728x90)
- Boombbox (336x280)
- Tiles (125x125)
- Skyscrapers (160x600)

## Targeted Design Centers

18 Chip Design centers focus on specific audiences with news, special features, technical articles, focus reports, blogs and more. iDesign provides engineers with weekly insights into the world of EDA and semiconductor chip development.

- > Architectural
- > DSP
- > Interface
- > Memory
- > Nanotechnology
- > SW Apps
- > ASIC-ASSP
- > ESL
- > IP
- > Methods
- > RF-Wireless
- > Tester - HW
- > DFM
- > FPGA's
- > Low Power
- > Mixed Signal
- > Structured ASIC
- > Verification



Sponsor a **ChipDesign** Design center and get exclusive ad placement, email broadcasts to targeted lists, content placements and increased brand awareness

### Diamond Sponsor - exclusive to one company per microsite

- > Rotating Leaderboard Banner for 12 months (50,000 guaranteed impressions)
- > One dedicated email broadcast (to minimum 20,000 qualified names)
- > 10 product pages or articles to post on microsite
- > UNLIMITED product announcements to post on microsite

### Platinum Sponsor - limited to two companies per microsite

- > Rotating Boombbox banner for 12 months (40,000 guaranteed impressions)
- > 8 product pages or articles to post on microsite
- > UNLIMITED product announcements to post on microsite

### Gold Sponsor - limited to eight companies per microsite

- > Rotating 125x125 banner for 12 months (50,000 guaranteed impressions)
- > 5 product pages or articles to post on microsite
- > UNLIMITED product announcements to post on microsite

## High Quality Lead Generation

■ **Chip Design White Paper Program**—Your white paper featured for three months on [www.chipdesignmag.com](http://www.chipdesignmag.com) and in 3 consecutive monthly email newsletters.

■ **Contest Sponsorship and Surveys**—Sponsor a contest, create a survey of up to 10 questions and generate leads including contact information and demographics.

## Blogs/Video Blogs

Interact directly with a targeted audience of chip designers by sponsoring your own blog!

## Webcasts

Webcasts offer a forum to bring content directly to design engineers and engineering managers. Webcasts bring moderated informational sessions directly to attendee's desktops with the capability to integrate messaging with audio and power point. Sponsorship includes visibility before and during the event, and a 12 month presence on our archives

### Webcast Schedule

Topic	Issue	Ad Deadline
FPGA Designs	April 2008	January, 18
IP Integration	June 2008	March 7
Low-Power-Design	Sept. 2008	June 14
Verification	Nov 2008	August 4

**Sponsor a ChipDesign webcast or create your own**

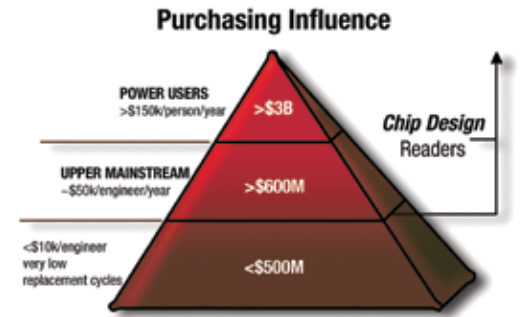
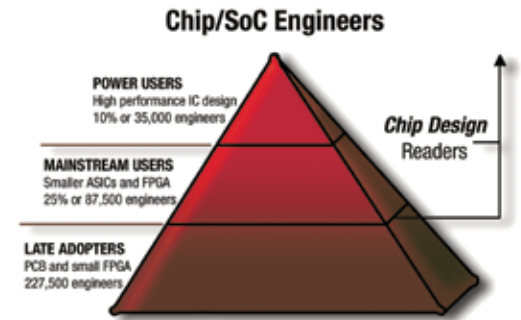
# Reach Powerful Buyers with Targeted Distribution

## 40,000 Important Readers

**Chip Design** is distributed in print to over 25,000 design engineers and engineering managers working on advanced SoC designs.

Each issue is also distributed electronically to an additional 15,000 design engineers/managers.

Chip Design's readers are chip, programmable logic device and IP-related architects, designers, and testers. The readership also includes software protocol-application engineers and technical program managers. These architect-design-test engineers and managers are responsible for creating the latest generations of ASICs, structured ASIC, ASSPs, FPGAs, memory cores and SoC devices.

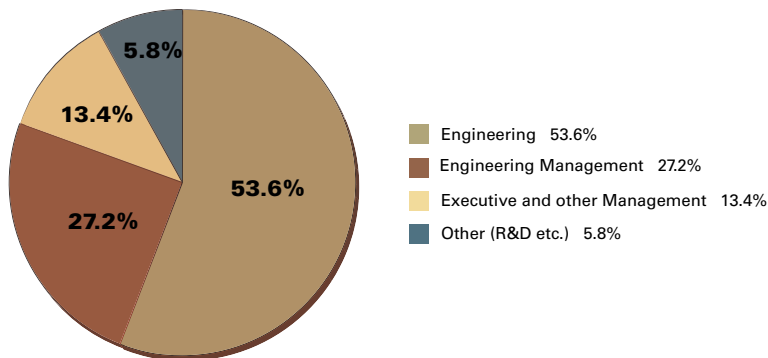


\*Source: Dataquest/Gartner

## Powerful Purchasing Influence

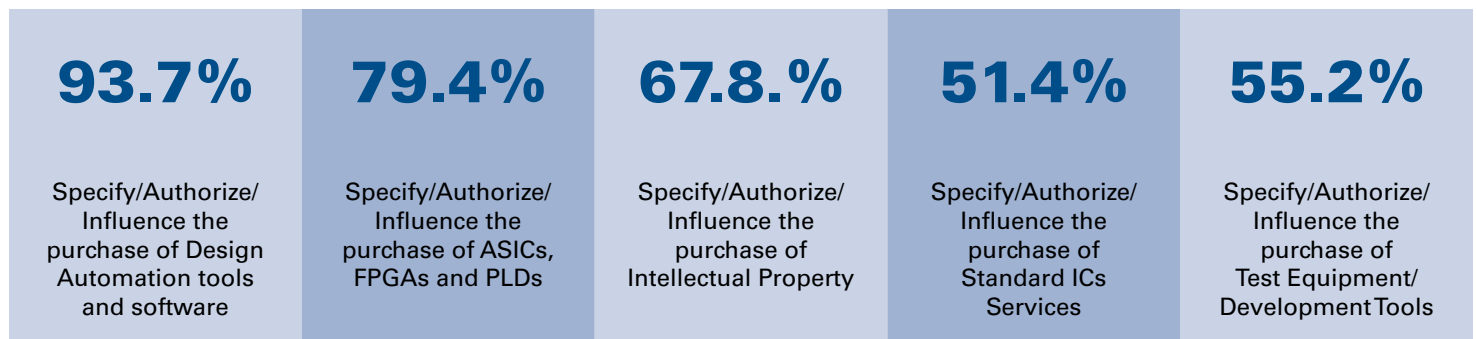
System architect, design and test engineers and engineering managers working on advanced SoC designs—**Chip Design** readers—account for a third of all design engineers. These key enablers influence the purchase of nearly 80% of the total EDA market—or about \$4 billion.

## Circulation Breakdown by Job Responsibility



Over 35% of **Chip Design** readers influence, specify or authorize the purchasing at companies with revenues of over \$500 million.

## Circulation Breakdown by Purchasing Responsibility



## Top 20 Subscribing Companies

AMCC AMD AMI Semiconductor Analog Devices	Broadcom Chartered Semiconductor Cisco Freescale	Fujitsu Hewlett-Packard IDT Infineon	Intel LSI Logic National Semiconductor NVIDIA	NXP Semiconductors Qualcomm ST Microelectronics Texas Instruments
--	---	---	--	--

# Special 2008 Marketing Opportunities

## Don't Be Left Out of these Important 2008 Annual Resource Catalogs

Resource Catalogs include valuable application articles, industry perspectives and comprehensive details on products, services and technologies in an easy to use data sheet format. Distributed in print, online and email newsletter formats each Resource Catalog is designed to help over **70,000** well-qualified engineers, embedded developers and chip designers make design trade-offs and purchasing decisions all year long.



### 2008 Resource Catalogs

Title	Pub Date	Space Deadline	Materials Deadline	Targeted Reach
<b>MIPS Embedded Resource Catalog</b>	March	February 27	March 3	Engineers, designers and embedded developers using the MIPS architecture
<b>IP Solutions Resource Catalog</b> <i>Intellectual property for IC Design and Verification</i>	April	March 25	March 28	SoC designers, verification, engineers and system architects
<b>Chip Design Resource Catalog</b>	June	May 19	May 22	Advanced IC designers
<b>PCI Express Solutions Resource Catalog</b>	November	Nov 7	November 14	Engineers and embedded developers using or considering PCI Express solutions
<b>Multicore Technologies Resource Catalogs</b>	September	August 25	August 29	Developers and engineers using multicore and multiprocessing Architectures
<b>FPGA and PLD Solutions Resource Catalog</b>	December	Dec 10	December 15	FPGA and PLD applications engineers

## Chip-Package-Board Conference – Fall 2008 in Silicon Valley

System-level design and manufacturing takes center stage in this one-of-a-kind conference that combines the technical depth, dedicated readership and broad sponsorship of both Chip Design and Embedded Intel® solutions print and online properties – including Trends Reports, IP Integrator and FPGA Designer publications. This timely conference will cover the embedded codesign-coverification, IP reuse, SIP, thermal, substrate, pin efficiency, hardware-software and analog-digital trade-off issues spanning the design and manufacturing of chip-package-board systems. Check the Chip Design website for information on keynote speakers, technical sessions and exhibitors.

## Put the Power of Custom Media to Work for You

**Customized Email/Newsletter Program:** Our teams do it all! Chip Design's editors will help customize your content, while our web design team places your banners and announcements, all of which goes to our subscriber list to reach your target markets. Optional Bonus: Additional distribution to email list you provide (up to 20,000) Custom email newsletter program: \$9,500 single edition rate \$ 7,500/4x rate

**Partner Marketing:** Promote your partner network and demonstrate the depth of market support with the Chip Design partner marketing programs

**Content Services:** Increase your audience and capture mindshare with compelling content.

**Micosites:** Combine custom content, vendor content and prepublished editorials to create a focused micosite designed to capture audiences and improve market share

**Custom Magazines and Catalogs:** Build a community, increase your visibility and reinforce your market position with a custom magazine or catalog. More affordable than you think!

# Chip Design Trends (CDT) Research

## Chip Design Trends (CDT) Biannual Report Key Findings from Latest Report

- Pre-Silicon design investigations grew by 18% compared to a year ago.
- New design activity surged in Europe, followed by increases in the Asia-Pacific region and relative flatness in North America.
- Increased use of semiconductor IP with analog-mixed signal and digital-core IP showing the largest segment growth – up by 35%!
- Hot markets included communications, data-processing and industrial-medical.
- Overwhelming evidence supports the slowing of Moore's Law!

## Basis of Report

- Over 44,000 unique, worldwide and regional pre-silicon design investigations
- Analysis and forecasting of key chip design metrics, including power, die size, clock speed, analog vs. digital IP, metal layers, technology nodes, memory usage and much more.

### Available Now!

Report ID: TB10235

Price: \$1,950 (One Issue); \$2,950 (Two Issue)

## Forecast the Future with Chip Design Trends (CDT) Custom Research Reports

### CDT Advantage:

- A growing aggregated database of over 44,000 unique pre-silicon, chip architectural design investigations – precursors to chip starts – containing important complex SoC metrics such as power, die area, clock speed, IP, processor-memory-interface cores, technology nodes, metal layer, regional user-market breakdowns and more.
- Access to the Chip Design property (print/online/e-Newsletters) readership, which represents leading Integrated device manufacturers (IDMs) – traditional chip design and manufacture vendor, fabless IP companies, EDA tool suppliers, semiconductor equipment vendors and foundries.
- As appropriate, access to the Chip Design affiliate sponsor subscribers, including leading chip, EDA and semiconductor organizations
- Chip Design's cadre of leading technology and business editors/analyst

### Methodology:

- Email/Web-based surveys and polls of Chip Design's over 45K targeted subscribers + affiliate sponsors.
- Data mining of and cross-referencing within our growing aggregated database of over 44,000 unique chip design metrics.
- Interview – phone and in person – with our subscribers and leading executives.
- Client involvement in tailoring and weighting of survey questions and data mining parameters
- Blind surveys, send to third party agents, are available

### Future Report Topics:

- ASIC Prototyping with FPGAs – Technology trends and regional/market segmentation
- Multicore challenges for memory, processors and buses designs
- Intellectual Property (IP) Usage – random-logic, embedded memory and non-memory, and I/Os
- Analog Mixed Signal (AMS) and RF-Wireless silicon trends
- Chip-Package-Board design and manufacturing trends and market profile
- Embedded SoC memory forecasts
- Design-for-Manufacturability (DFM) tools survey

### Pricing:

- Multi Client: \$9,500
- Single Sponsor: \$15,000

To Learn more contact: Melissa Sterling at 415.970.1910 or msterling@extensionmedia.com

Section I, Chapter 2

Chip Design Trends Biannual Report

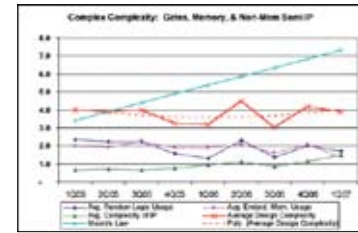


Figure 15: The complexity quotient is tracked for gates, memory, and cores.

Figure 15 paints a very telling picture—much like what we saw for the relative divergence in highest clock speed in Figure 9 relative to what would be anticipated for Moore's Law. In an attempt to narrow the gap, one may choose to massage our assumptions or shift the relative comparison point, etc. At the end of the day, however, the conclusions from the data (and related analysis) seem incontrovertible. Average design complexity has, at best case, been flat around 4.0 MGates for the past two years. A reasonable extrapolation of Moore's Law should be yielding an average north of 7.0 MGates in the first quarter of 2007.

#### SEMICONDUCTOR-IP USAGE: IS THE TREND ONE'S FRIEND?

At a broader level, Figure 16 demonstrates that the usage of "more than 80% hard IP" has stabilized in the past two quarters and may actually be trending higher. We aren't necessarily wedded to any notion of hard IP being more desirable than soft IP. It's merely interesting to note that the relative quotient of hard IP was nearly 80% back in the first quarter of 2005. Recently, though, it seems to be settling around 70%.

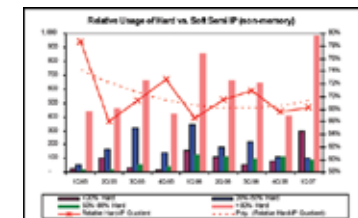


Figure 16: Is the usage of "mostly hard IP" making a comeback?

All print and electronic rights are the property of Chip Design © 2007

17

# Participate on a regular basis with premium display advertising, data sheets, inserts, advertorials, conference exhibits and sponsorships

## Save 25% on Print and Online Issues – place your order before December 31, 2007

	1 X RATE	3 X RATE	6 X RATE
Full Page	\$4,500	\$4,125	\$3,750
2-Page Spread	\$6,500	\$5,800	\$5,000
1/2 Page (horiz. or vertical)	\$3,050	\$2,775	\$2,500
1/3 Page (vertical only)	\$2,150	\$1,900	\$1,700
1/4 Page	\$1,625	\$1,440	\$1,275

### Add this percentage for Premium Positions

Back Cover - 20%
Inside Front Cover - 15%
Inside Front Cover Spread - 15%
Opposite Inside Front Cover (1st right page) - 10%
Inside Back Cover - 5%
Opposite ToC - 5%
Opposite Editorial Page - 5%
Center Fold 2-Page Spread - 5%

### Solution Provider Advertorials / White papers

Showcase your company as an important solutions provider with articles, case studies, and white papers positioned in the special *Solution Provider* section of Chip Design magazine, on www.chipdesignmag.com and in the email newsletters.

	1 X RATE	3 X RATE	6 X RATE
1-Page Article	\$2,500	\$2,000	\$1,500
2-Page Article (spread w/Ad okay)	\$4,500	\$3,500	\$2,500

### Product Showcase

	1 X RATE	3 X RATE	6 X RATE
Full Page Data Sheet	\$3,000	\$2,250	\$1,500
1/2 Page	\$2,000	\$1,500	\$750
1/4 Page	\$950	\$855	\$750

### Recruitment Advertising

	1 X RATE	3 X RATE	6 X RATE
1/2 Page Classified Ad	\$895	\$670	\$500
1/4 Page Classified Ad	\$495	\$370	\$300
1/8 Page Classified Ad	\$275	\$250	\$200

## Chip Design Magazine - Online Only Issues - Saves 25% Place an order before December 31, 2007

### Diamond Sponsor (1 Company Only)

- > Leaderboard Banner on issue's home page
- > Leaderboard Banner on email announcing release of issue (over 40,000)
- > Promote with headline links up to 5 white papers or data sheets on issue's homepage and email announcement
- > Logo on cover identified as Diamond Sponsor
- > Back cover display ad
- > \$7,500 per issue or \$5,000 6x rate

### Platinum Sponsor (3 Companies Only)

- > Rotating Skyscraper Banner on that issue's home page
- > 125x125 banner on email announcing release of issue (over 40,000)
- > Promote with headline links up to 3 white papers or data sheets
- > Logo on cover identified as Platinum Sponsor
- > Premium position display ad
- > \$5,000 per issue or \$4,000 6x rate

### Gold Sponsor (5 Companies Only)

- > Rotating Boombox Banner on that issue's home page
- > 125x125 banner on email announcing release of issue (over 40,000)
- > Promote with headline links up to 1 white papers or data sheets
- > Logo on cover identified as Gold Sponsor
- > One display ad in online issue
- > \$2,500 per issue or \$2,000 6x rate

## Resource Catalogs (save 35% - place your order before December 31st)

DATA SHEETS	Standard Rate	Add Color
1st Full Page Data Sheet	\$1,495	\$250
Each Additional Full Page Data Sheet	\$1,175	\$250
Matrix Page	\$2,000	\$250
1/2 Page Data Sheet	\$995	\$150

DISPLAY ADS/ADVERTORIALS	Standard Rate	Add Color
2 Page Spread, Black and White	\$3,750	\$400
1- Page, Black and White	\$2,750	\$300
1/2 Page (Horiz.), Black and White	\$2,000	\$250
1/4 Page, Black and White	\$975	\$150

### DIAMOND SPONSORSHIP (exclusive to one company per catalog)

\$17,000

- > Logo on catalog cover (top right corner) on the online catalog microsite homepage
- > 10 pages (4-color) in print catalog to use as Display Ads, Data Sheets or Advertorials
- > Guaranteed Display Ad Position Back Cover
- > Rotating 728x90 Leaderboard banner on catalog microsite home page for 12 months(50,000 guaranteed impressions)
- > (1) dedicated email broadcast (minimum 15,000 qualified names)

### PLATINUM CO-SPONSORSHIP (limited to two companies per catalog)

\$12,500

- > Logo on catalog cover and online catalog microsite homepage
- > 8 pages (4-color) in print catalog to use as Display Ads, Data Sheets or Advertorials
- > Guaranteed Display Ad Position (Inside Front Cover or Page 1)
- > Rotating 125x125 Ad banner on catalog microsite home page for 12 months (40,000 guaranteed impressions)

### GOLD CO-SPONSORSHIP (limited to 8 companies per catalog)

\$10,000

- > Logo on catalog cover and online catalog microsite homepage
- > 5 pages (4-color) in print catalog to use as Display Ads, Data Sheets or Advertorials
- > Guaranteed Display Ad Position (Opposite TOC 1 & 2, Opposite Intro, Opposite Advertorials)
- > Rotating 125x125 Ad banner on catalog microsite home page for 12 months (50,000 guaranteed impressions)

### DELUXE PRINT/ONLINE PACKAGE

\$6,250

- > 4 pages (4-color) to use as Display Ads, Data Sheets or Advertorials
- > 125x125 rotating Ad Banner on catalog microsite home page for 3 months

## Chip - Package - Board Conference - Fall 2008 in Silicon Valley

### Sponsor and Table - Top Exhibitors Rates

- Diamond Sponsor - 1 company only \$10,000
- Platinum sponsors - 3 companies only \$7,500
- Gold sponsors - 5 companies only \$5,000
- TableTop Exhibit - \$2,500

### Attend the Conference!

- \$349 - Full 2 day Conference Package
- \$199 - One day conference Package

# Participate with Online and Interactive Advertising, Email Newsletter Advertising, Lead Generation Programs and Sponsorships

## Internet Advertising

### Banners on www.chipdesignmag.com

	Pixel Size	Rate(CPM)
Boom Box	336x280	\$200
Skyscraper	120x600	\$175
Leaderboard	728X90	\$175
Tile Banners	125x125	\$75

### Lead Generation Programs

Rate

- > Chip Design White Paper Program \$1000  
per month
- > Custom Microsites - (3 month minimum) \$2,000  
per month
- > Contest/Survey Sponsorships - (3 month minimum) \$2,000  
per month

### Sponsored Blog Participation

- ▶ \$1000 per month (3 month minimum)

### Webcast sponsorships

- ▶ Vendor sponsored \$9,500

### ChipDesign Webcasts

- ▶ Diamond Sponsor (one only) \$7,500
- ▶ Platinum Sponsor (three only) \$4,950

### Design Centers and iDesign Sponsorships

Save 35% - Place your order before  
December 31st

#### Diamond Sponsor - exclusive to one company per microsite \$17,500/12 months

- > Rotating Boombox Banner for 12 months (50,000 guaranteed impressions)
- > One dedicated email broadcast (to minimum 20,000 qualified names)
- > 10 product pages or articles to post on microsite
- > UNLIMITED product announcements to post on microsite

#### Platinum Sponsor - limited to two companies per microsite \$12,500/12 months

- > Rotating Boombox banner for 12 months (40,000 guaranteed impressions)
- > 8 product pages or articles to post on microsite
- > UNLIMITED product announcements to post on microsite

#### Gold Sponsor - limited to eight companies per microsite \$10,000/12 months

- > Rotating 125x125 banner for 12 months (50,000 guaranteed impressions)
- > 5 product pages or articles to post on microsite
- > UNLIMITED product announcements to post on microsite

## Email Newsletter Sponsorships

**EMAIL ONLY**

#### Roadblock/exclusive Limited to one sponsor

468x60 banner at top center position; side banner 125 x up to 728; up to three text ads; up to five industry announcements.  
Optional bonus: additional distribution to your email lists (up to 20,000)

\$7,500/issue

#### Platinum Sponsor

728x90 Leaderboard banner at top center position and first text ad

\$3,000/issue

#### Gold Sponsor

Skyscraper top right banner position and second text ad

\$2,500/issue

#### Silver Sponsor

First 125x125 banner position third text ad

\$2,000/issue

#### Bronze Sponsor

Second 125x125 banner position fourth text ad

\$1,500/issue

**Extension  
MEDIA**

#### About Extension Media

Extension Media is a publisher of business-to-business magazines, resource catalogs and web sites that address high-technology industry platforms and emerging technologies such as embedded systems, chip design, intellectual property, software and infrastructure, architectures and operating systems.

## CONTACTS

#### Advertising / Marketing

Karen Popp  
Associate Publisher, Sales Director  
415.305.5557  
kpoppp@extensionmedia.com

Marcy Carnerie  
Sales Manager  
510.919.4788  
mcarnerie@extensionmedia.com

#### Article / Abstract Submission

John Blyler  
Editor-in-Chief  
503.614.1082  
jblyler@extensionmedia.com

1786 18th Street  
San Francisco, CA 94107  
Tel: +1 415.255.0390  
Fax: +1 415.255.9214  
www.extensionmedia.com